















PREPARATION METHOD

PRINTED CIRCUIT BOARD (ASSEMBLED)

 CUTTING		Equipment QATM Qcut / Brillant	Consumable Cut-off wheel: diamond, metal bond Anti-corrosion coolant				
 MOUNTING		Equipment Pressure vessel	Consumable KEM 20, KEM 90			Method Cold mounting	
 GRINDING/ POLISHING		Equipment QATM Qpol / Saphir Sample size \varnothing 40 mm					
STEP	MEDIUM		 rpm		 N	 min	
 Planar grinding	SiC-paper/foil P320 (180), GALAXY green*	H ₂ O	250-300	▶▶ Synchronous rotation	30	Until plane (slightly before point of interest)	
 Grinding	SiC-paper/foil P600 (400), GALAXY blue*	H ₂ O	250-300	▶▶ Synchronous rotation	25	1:00 (until point of interest)	
 Grinding	SiC-paper/foil P1200 (600), GALAXY yellow*	H ₂ O	250-300	▶▶ Synchronous rotation	25	1:00 (until point of interest)	
 Pre-polishing	ALPHA/BETA	Dia Complete Poly, 9 μ m	120-150	◀▶ Counter rotation	25	4:00	
 Polishing	GAMMA/DELTA	Dia Complete Poly, 3 μ m	120-150	▶▶ Synchronous rotation	30	4:00	
 Final polishing	ZETA/OMEGA	Eposal, 0.06 μ m	120-150	◀▶ Counter rotation	25	1:30 (H ₂ O during final 0:30)	

* For printed circuit boards with ceramic components